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Photonic integrated circuits –
Part 1: Introduction and roadmap for standardization

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CONTENTS

FOREWORD.....5
1 Scope.....7
2 Normative references.....7
3 Terms and definitions.....7
4 Photonic integrated circuit (PIC).....9
4.1 Overview.....9
4.2 PIC families.....11
4.2.1 General.....11
4.2.2 Silicon photonics.....12
4.2.3 III-V photonics.....12
4.2.4 Silica and silicon nitride PICs.....12
4.3 Manufacturing capabilities.....13
4.4 Global market.....13
4.5 Global government investment in PIC research and development.....13
4.5.1 General.....13
4.5.2 United States of America.....13
4.5.3 Europe.....13
4.5.4 Japan.....13
5 Silicon photonics.....14
5.1 Overview.....14
5.2 Integration schemes.....14
5.2.1 General.....14
5.2.2 Heterogeneous integration.....15
5.2.3 Homogenous integration.....15
5.3 Non-linear behaviour.....15
6 III-V photonics.....15
6.1 Indium phosphide (InP) photonics.....15
7 PIC transceiver – A simple example.....17
7.1 Overview.....17
7.2 Transmitter section.....17
7.3 Receiver section.....18
8 Optical sources.....19
8.1 Overview.....19
8.2 Advances in III-V integration onto silicon PICs.....19
8.3 Vertical cavity surface emitting lasers (VCSELs).....20
9 Optical receivers.....20
10 Modulators.....21
10.1 Overview.....21
10.2 Common modulator structures.....21
10.3 Plasma dispersion effect.....22
10.4 Plasmonics.....23
10.5 Silicon organic hybrid.....23
11 Switches.....24
11.1 Overview.....24
11.2 Mach-Zehnder interferometers (MZI).....24
11.3 Micro-ring resonator (MRR).....24

11.4 Double-ring assisted MZI (DR-MZI) 25
12 3D integration 25
12.1 Optochip 25
12.2 Through-silicon-vias (TSVs) 25
12.3 Hybrid integration process example 26
12.4 Flip-chip bonding 26
12.5 State of the art in 3D research and development 27
13 Commercial state of the art 27
13.1 Overview 27
13.2 Luxtera 27
13.3 Intel 28
13.4 Mellanox 28
13.5 Oracle 29
13.6 IBM 29
13.7 Photonics Electronics Technology Research Association (PETRA) 29
14 PIC coupling interfaces 30
14.1 Overview 30
14.2 Grating coupler 30
14.3 Adiabatic coupling 33
14.4 Butt coupling 35
14.5 Orthogonal chip-to-fibre coupling 35
15 Electrical interface 36
16 Packaging 37
17 Standardization roadmap 37
Bibliography 39

Figure 1 – Examples of PICs [1] 11
Figure 2 – Optical beam forming network fabricated in TriPleX (silicon nitride) 12
Figure 3 – Typical silicon waveguides [6] 14
Figure 4 – Heterogeneous integration by flip chip and copper pillars 15
Figure 5 – Indium phosphide PIC with many structures, including AWG 16
Figure 6 – Combined InP and TriPleX microwave photonic beam-forming network 17
Figure 7 – Schematic of four channel PIC transceiver by Luxtera [6] 18
Figure 8 – Schematic view of 3D assembly of PIC + EIC electro-optical assembly [6] 20
Figure 9 – Example of Ge-on-Si photodetector formed by germanium selective epitaxy [6] 21
Figure 10 – High speed PN modulator [6] 22
Figure 11 – PETRA optical I/O core chip modulation scheme 23
Figure 12 – Silicon organic hybrid 24
Figure 13 – 4 x 4 switching matrix PIC attached to PCB with wire bonds on the EU FP7 PhoxTroT project 25
Figure 14 – EU FP7 project PhoxTroT 3D integrated optochip concept 26
Figure 15 – LIFT principle 27
Figure 16 – PETRA optical I/O core performance at 25 Gb/s 29
Figure 17 – Examples of vertical grating couplers [6] 31
Figure 18 – Coupling efficiency of single polarization grating coupler (SPGC) at 1 310 nm and 1 490 nm [91] 32

Figure 19 – Composite coupling interfaces on PETRA optical I/O core ... 32
Figure 20 – Assembly for adiabatic optical coupling between Si photonics chip and SM polymer waveguide ... 33
Figure 21 – Flip-chipped silicon photonic chip onto polymer waveguide substrate using adiabatic coupling ... 34
Figure 22 – Bidirectional optical coupling between SOI waveguides and single polymer waveguides ... 35
Figure 23 – Design of the mirror plug assembly ... 36
Figure 24 – Typical operative framework of silicon-photonics modules ... 37
Figure 25 – PIC standardization roadmap ... 38

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PHOTONIC INTEGRATED CIRCUITS –

Part 1: Introduction and roadmap for standardization

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The text of this Technical Report is based on the following documents:

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Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 63072-1 series, published under the general title *Photonic integrated circuits*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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PHOTONIC INTEGRATED CIRCUITS –

Part 1: Introduction and roadmap for standardization

1 Scope

This part of IEC 63072, which is a Technical Report, provides an introduction to photonic integrated circuits (PICs) and describes a roadmap for the standardization of PIC technology over the next decade.

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2 Normative references

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